Display Elektronik GmbH

DATA SHEET

TFT MODULE

DEM 480800A3 VMH-PW-N

4,0" TFT

Product Specification

Ver.: 1

Revision History

Revision	Date	Originator	Detail	Remarks
0	21.09.2018	ZDT	Initial Release	-
			Add Weight	P4
1	10.11.2018	WQ	Modify Current Consumption	P5
'	10.11.2016	VVQ	Modify Optical Characteristics	P6
			Modify Outline Drawing	P24

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size (Diagonal)	4.0"	-
LCD Type	MVA TFT	-
Display Mode	Transmissive / Normally Black	-
Resolution	480 x RGB x 800	Pixels
View Direction	Full Viewing	Best Image
Module Outline	56.14 x 95.50 x 1.80 (Note1)	mm
Active Area	51.84 x 86.40	mm
Pixel Pitch	0.108 x 0.108	mm
Pixel Arrangement	RGB Vertical Stripe	-
Display Colors	16.7 Million	-
Interface	3-Wire-SPI + 24-Bit-RGB	-
Driver IC	ST7701S (Sitronix)	-
With or without Touch Panel	without	-
Operating Temperature	-20°C to +70°C	°C
Storage Temperature	-30°C to +80°C	°C
Weight	~ 22	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

Vss=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Power Supply	VCC	-0.3	3.6	V
Storage Temperature	T _{STG}	-30	+80	°C
Operating Temperature	Top	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	
Power Supply	VCC	2.5	2.8	3.6		
Logic Low Input Voltage	VIL	GND	-	0.3*VCC	V	
Logic High Input Voltage	V _{IH}	0.7*VCC	-	VCC	V	
Logic Low Output Voltage		Vol	GND	-	0.2*VCC	V
Logic High Output Voltage		Vон	0.8*VCC	-	VCC	V
Current Consumption	Logic	loo lin		40	-	mΛ
all White	Analog	ICC+ IIN	<u> </u>	40		mA

5. Backlight Characteristic

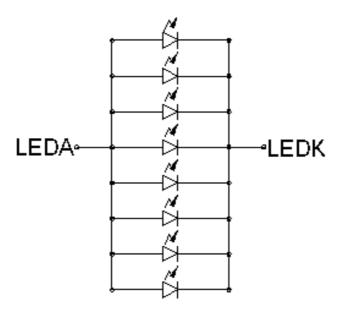
5.1. Backlight Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	Ta=25 °C, I _F =15mA/LED	2.8	3.2	3.4	V
Forward Current	lF	Ta=25 °C, V _F =3.2V/LED	-	120	-	mA
Power Dissipation	Po	-	-	384	-	mW
Uniformity	Avg	-	70	80	-	%
LED Lifetime (25°C)			20000	30000	-	Hrs
Drive Method	Constant Current					
LED Configuration		8 White LEDs (8xLE	Ds in Par	allel)		

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25°C±2°C, 60%RH±5%, I_F=15mA/LED.

5.2. Backlighting Circuit



6. Touch Screen Panel Specifications

without Touch

7. Optical Characteristics

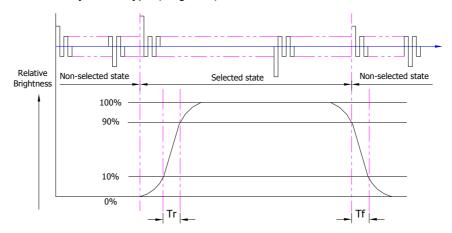
7.1. Optical Characteristics

Ta=25°C, VCC=2.8V

	Item		Symbol	Condition	S	Specification		
			Syllibol	Condition	Min.	Тур.	Max.	Unit
	Luminan	ce on						
($TFT(I_f \!=\! 15r$	mA/LED)	Lv	Normally	240	300	-	cd/m²
ode	Contrast Ratio	(See 7.3)	CR	viewing angle	600	800	-	
Backlight On (Transmissive Mode)	·	onse Time T_{R+TF} ee 7.2) $\theta x = \phi Y = 0^{\circ}$	$\Theta X = \Psi Y = 0^{\circ}$	-	25	30	ms	
inis		Dod	XR		0.590	0.640	0.690	
ans	Chromaticity Transmissive	Red	YR		0.292	0.342	0.392	
Ē		Green	XG		0.265	0.315	0.365	
On			YG		0.593	0.643	0.693	
ght	(See 7.5)		Хв		0.092	0.142	0.192	
K K	(000 7.0)		ΥB		0.032	0.082	0.132	
Зас		White	Xw		0.248	0.298	0.348	
_		VVIIILE	Yw		0.301	0.351	0.401	
		Horizontal	θx+		70	80	-	
	Viewing Angle	Tionzoniai	θx-	Center CR≥10	70	80	-	Deg.
	(See 7.4)	Vertical	φΥ+	Center CIVE 10	70	80	-	Deg.
		vertical	φY-		70	80	-	
	NTSC Ratio	(Gamut)			65	70	-	%

7.2. Definition of Response Time

7.2.1. Normally Black Type (Negative)



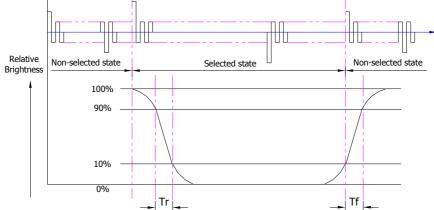
Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

7.2.2.

Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

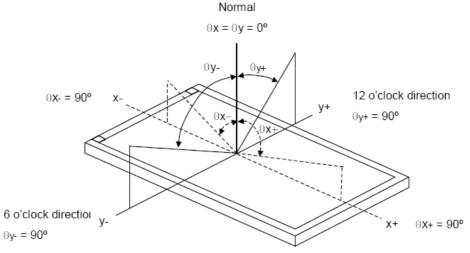
7.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent		
Measuring Point Diameter	3mm//1mm		
Measuring Point Location	Active Area centre point		
Toot pottorn	A: All Pixels white		
Test pattern	B: All Pixel black		
Contrast setting	Maximum		

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

7.4. Definition of Viewing Angles

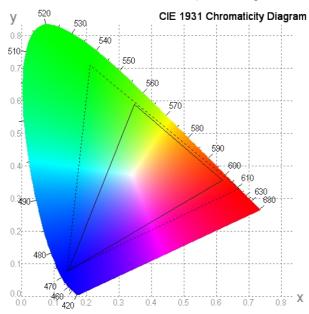


Measuring machine: LCD-5100 or EQUI

7.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

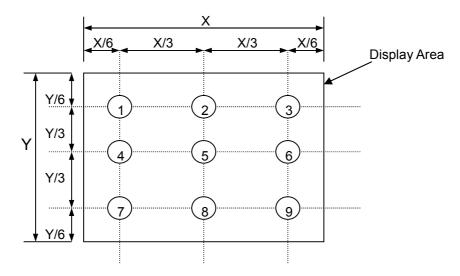


7.6. Definition of Surface Luminance, Uniformity and Transmittance

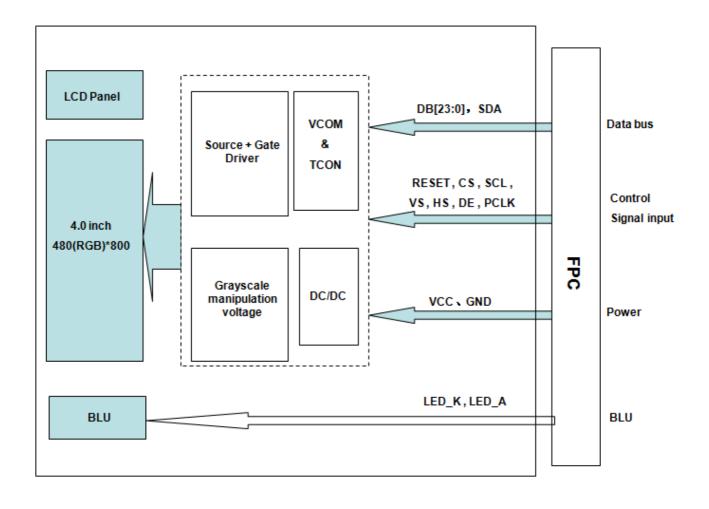
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 7.6.1. Surface Luminance: L_V = average (L_{P1} : L_{P9})
- 7.6.2. Uniformity = Minimal $(L_{P1}:L_{P9})$ / Maximal $(L_{P1}:L_{P9})$ * 100%
- 7.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



8. Block Diagram and Power Supply

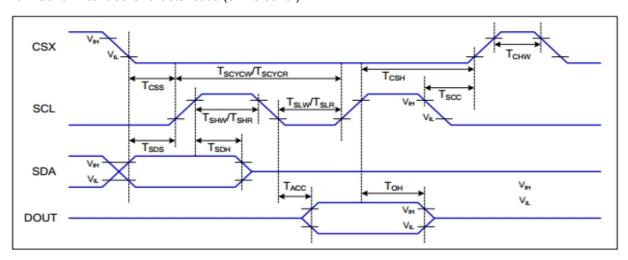


9. Interface Pins Definition

No.	Symbol	Function	Note
1	LED-A	Anode	
2	LED-K	Cathode	
3	RESET	The external reset input	
4	VCC	Power supply	
5	CS	A chip select signal. Low: the chip is selected and accessible	
6	SCL	Serial clock	
7	SDA	Serial data input/output bidirectional pin for SPI Interface	
8	GND	Ground	
9	PCLK	Dot clock signal for RGB interface operation	
10	GND	Ground	
11	VS	Frame synchronizing signal for RGB interface operation	
12	HS	Line synchronizing signal for RGB interface operation	
13	DE	Data enable signal for RGB interface operation	
14	GND	Ground	
15	DB0		
16	DB1		
17	DB2		
18	DB3		
19	DB4		
20	DB5		
21	DB6		
22	DB7		
23	DB8		
24	DB9		
25	DB10		
26	DB11	24-bit parallel data bus for RGB Interface	
27	DB12	24-bit paraller data bus for NOB interface	
28	DB13		
29	DB14		
30	DB15		
31	DB16		
32	DB17		
33	DB18		
34	DB19		
35	DB20		
36	DB21		
37	DB22		
38	DB23		
39	GND	Ground	
40	GND	Ground	

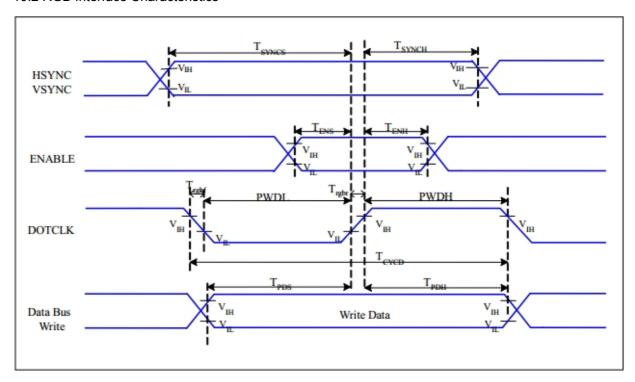
10. AC Characteristics

10.1 Serial Interface Characteristics (3-line serial):



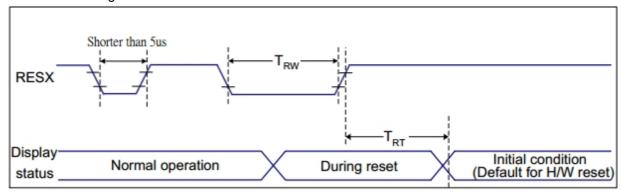
Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	60		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
SCL	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	

10.2 RGB Interface Characteristics



Signal	Symbol	Parameter		MAX	Unit	Description
HSYNC, VSYNC	T _{SYNCS}	VSYNC, HSYNC Setup Time	5	-	ns	
ENABLE	T _{ENS}	Enable Setup Time	5	-	ns	
ENABLE	T _{ENH}	Enable Hold Time	5	-	ns	
	PWDH	DOTCLK High-level Pulse Width	15	-	ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	15	-	ns	
DOTCLK	T _{CYCD}	DOTCLK Cycle Time	33	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	15	ns	
DB	T _{PDS}	PD Data Setup Time	5	-	ns	
DB	Тррн	PD Data Hold Time	5	-	ns	

10.3 Reset Timing:



Related Pins	Symbol Parameter		MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Paget cancel	-	5 (Note 1, 5)	ms
		Reset cancel		120(Note 1, 6, 7)	ms

Notes:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
 - 2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action	
Shorter than 5us	Reset Rejected	
Longer than 9us	Reset	
Between 5us and 9us	Reset starts	

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.
 - 4. Spike Rejection also applies during a valid reset pulse as shown below:

11. Quality Assurance

11.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

11.2. Standard for Quality Test

11.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2. Sampling Criteria:

Visual inspection: AQL 1.5%

Electrical functional: AQL 0.65%.

11.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

11.3. Nonconforming Analysis & Disposition

- 11.3.1. Nonconforming analysis:
 - 11.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
 - 11.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
 - 11.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.
- 11.3.2. Disposition of nonconforming:
 - 11.3.2.1. Non-conforming product over PPM level will be replaced.
 - 11.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

11.4. Agreement Items

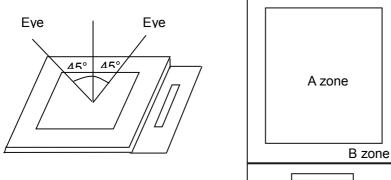
Shall negotiate with customer if the following situation occurs:

- 11.4.1. There is any discrepancy in standard of quality assurance.
- 11.4.2. Additional requirement to be added in product specification.
- 11.4.3. Any other special problem.

11.5. Standard of the Product Visual Inspection

11.5.1. Appearance inspection:

- 11.5.1.1. The inspection must be under illumination about $1000 1500 \, lx$, and the distance of view must be at $30 \, cm \pm 2 \, cm$.
- 11.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.
- 11.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



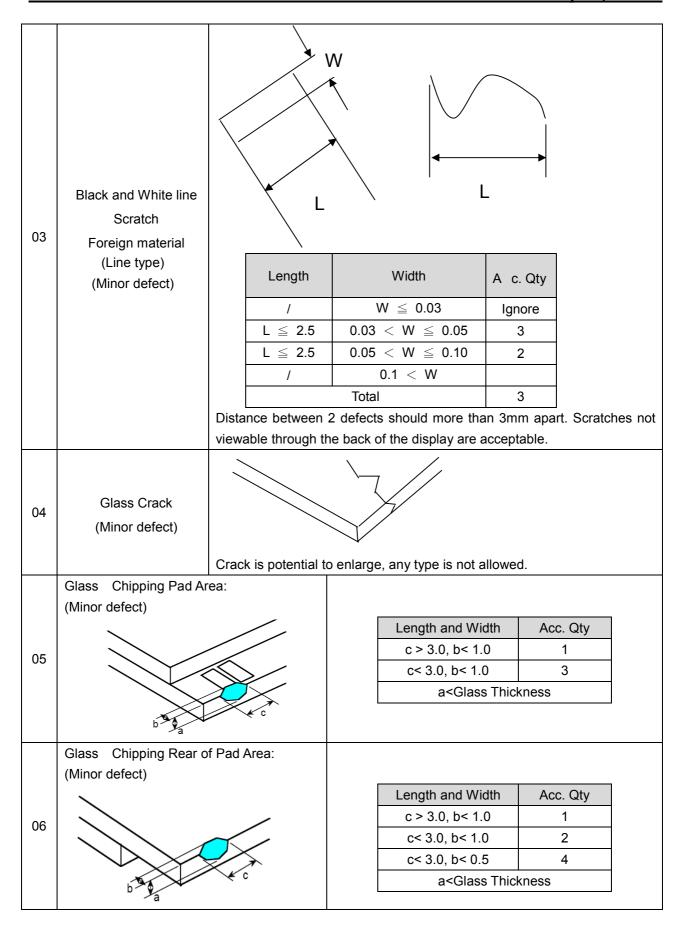
11.5.2. Basic principle:

11.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

11.5.2.2. New item must be added on time when it is necessary.

11.6.Inspection Specification

No	Item	Criteria (Unit: mm)			
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	φ= (a + b) /2 Distance between 2 defects sh	Area Size		Acc. Qty Ignore 2 1 0 2 no include φ≤ 0.10
02	Electrical Defect (Minor defect)	Bright dot 0 Dark dot N Total dot Not vis Remark: 1. Bright dot caused by scra	$\begin{array}{c c} 0 & 0 \\ \leqslant 2 & N \leqslant 2 \\ \leqslant 2 & N \leqslant 2 \\ \text{sible through 5% ND filter} \end{array}$		



	Class Chinning Evert Red Area:				
	Glass Chipping Except Pad Area:				
07	(Minor defect)	Length and Width	Acc. Qty		
		c > 3.0, b< 1.0	1		
		c< 3.0, b< 1.0	2		
		c< 3.0, b< 0.5	4		
	b	a <glass td="" thick<=""><td></td></glass>			
	₩ Zec				
	a ^ /				
	Glass Corner Chipping:				
	(Minor defect)				
		Length and Width	Acc. Qty		
00		c < 3.0, b< 3.0	Ignore		
80		a <glass td="" thick<=""><td>rness</td></glass>	rness		
	b				
	Glass Burr:				
	(Minor defect)				
		Length	Acc. Qty		
		F < 1.0	Ignore		
09	F				
	F	Glass burr don't affect as	semble and module		
	→	dimension.	semble and module		
	FPC Defect:				
	(Minor defect)				
	2 >: ->	10.1 Dent, pinhole width a <w 3.<="" td=""></w>			
10		(w: circuitry width.)			
	$w \rightarrow \bigcirc \longleftarrow$	10.2 Open circuit is unacceptable.			
		10.3 No oxidation, contamination	n and distortion.		
	a→←				

			Diameter	Acc. Qty		
	Bubble on Polarizer		φ≤0.20	Ignore		
11			0.20 <φ≤0.30	4		
	(Minor defect)		0.30 <φ≤0.50	1		
			0.50 < φ	None		
					•	
			Diameter	Acc. Qty		
	Dent on Polarizer		φ≤0.20	Ignore		
12	(Minor defect)		0.20 <φ≤0.30	4		
	(minor derect)		0.30 <φ≤0.50	1		
			0.50 < φ	None		
40	D I	13.1 No rust, distort	ion on the Bezel.			
13	Bezel	13.2 No visible finge	erprints, stains or other	contamination.		
		D: Diameter W: wi				
		14.1 Spot: D<0.25 is	· ·			
		0.25≤D≤0	·			
		2dots are acceptable and the distance between defects should more the			hould more than 10	
			e and the distance bei	ween delects s	nodia more trian 10	
14	Touch Panel	mm.				
14	Touch Fanel		unacceptable			
		14.2 Dent: D>0.40 is	•			
		14.3 Scratch: W≤0.03, L≤10 is acceptable,				
		0.03 <w≤0.10, acceptable<="" is="" l≤10="" td=""></w≤0.10,>				
		Distance between 2 defects should more than 10 mm.				
		W>0.10 is unacceptable.				
		15.1 No distortion of	r contamination on PC	B terminals.		
15	PCB	15.2 All componer	nts on PCB must sa	me as docume	ented on the	
15		BOM/component lay	yout.			
		15.3 Follow IPC-A-6	600F.			
16	Soldering	Follow IPC-A-610C	standard			
		The below defects n	nust be rejected.			
		17.1 Missing vertical / horizontal segment,				
		17.2 Abnormal Display.				
	Electrical Defect	17.3 No function or no display.				
17	(Major defect)	17.4 Current exceeds product specifications				
	(-)	17.5 LCD viewing a	ngle defect.			
		17.6 No Backlight.				
		17.7 Dark Backlight				
		17.8 Touch Panel no	o function.			

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

11.7. Classification of Defects

- 11.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 11.7.2. Two minor defects are equal to one major in lot sampling inspection.

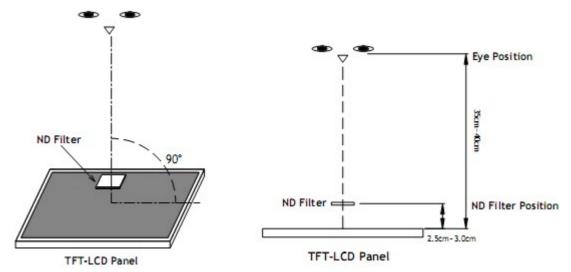
11.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

11.9. Packaging

- 11.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 11.9.2. Modules inside package box should have compliant mark.
- 11.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

12. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	+70°C, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	+50°C, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	+80°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min ~ +70°C, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	2	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: \pm 4kV 150pF/330 Ω 5 times	- 2	GB/T17626.2 -2006
		Contact: ± 2 kV 150pF/330 Ω 5 times		
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

13. Precautions and Warranty

13.1. Safety

- 13.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 13.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

13.2. Handling

- 13.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 13.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

13.3. Storage

- 13.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 13.3.2. Strong light exposure causes degradation of polarizer and color filter.

13.4. Metal Pin (Apply to Products with Metal Pins)

- 13.4.1. Pins of LCD and Backlight
 - 13.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering
 - 13.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

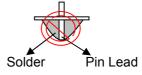
Recommended Soldering Temp: 350±20 ℃

Typical Soldering Time: ≤3s

13.4.1.3. Solder Wetting

Solder Pin Lead

Recommended



Not Recommended

13.4.2. Pins of EL

- 13.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.
- $13.4.2.2.\ No\ Solder\ Paste\ on\ the\ soldering\ pad\ on\ the\ mother board\ is\ recommended.$
- 13.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290 ℃

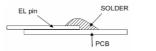
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

13.4.2.4. No horizontal press on the EL leads during soldering.

13.4.2.5. 180° bend EL leads three times is not allowed.

13.4.2.6. Solder Wetting



EL pin SOLDER PCB

Recommended

Not Recommended

13.4.2.7. The type of the solder iron:



Recommended

Not Recommended

13.4.2.8. Solder Pad



13.5. Operation

- 13.5.1. Do not drive LCD with DC voltage
- 13.5.2. Response time will increase below lower temperature
- 13.5.3. Display may change color with different temperature
- 13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 13.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 13.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 13.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 13.5.8. Do not display the fixed pattern for long time(we suggest the time not longer than one hour) because it may develop image sticking due to the TFT structure.

13.6. Static Electricity

- 13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 13.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

13.7. Limited Warranty

- 13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

14. Outline Drawing

